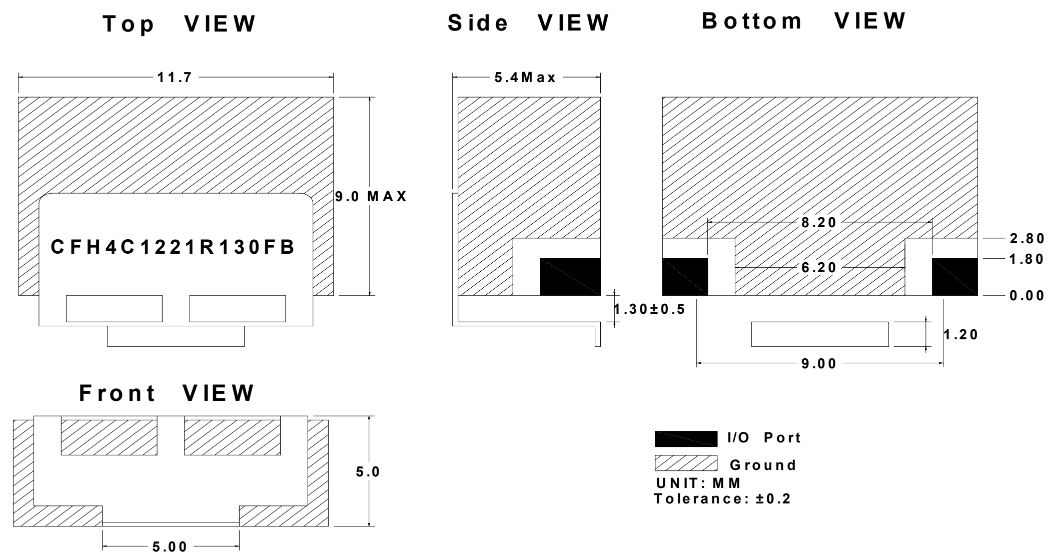
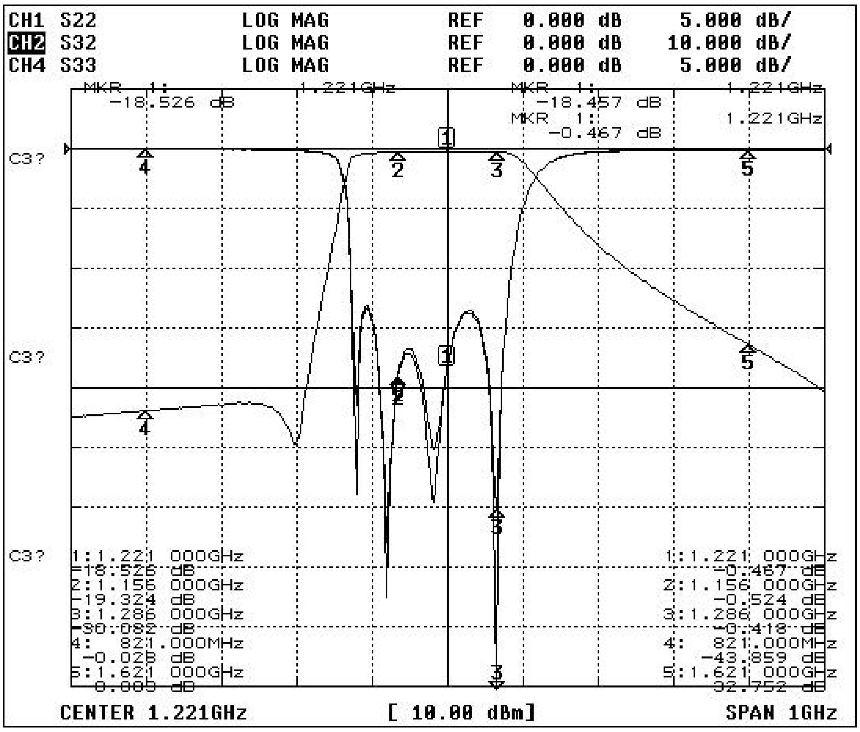
Electrical Specification

ITEMS	SPEC	UNIT
Center Frequency [fo]	1221.0	MHz
Bandwidth [BW]	fo ±65.0 [1156.0 ~ 1286.0]	MHz
Insertion Loss in BW	0.6	dB max
Ripple in BW	0.5	dB max
Return Loss in BW	15.0	dB min
Attenuation ☑ Absolute Value ☐ Relative Value	25.0 dB min @ fo -400.0 [821.0 ~]	MHz
	25.0 dB min @ fo +400 [1621.0 ~]	MHz
	dB min @ fo ± [&]	MHz
	dB min @ fo ± [&]	MHz
Group Delay Variation		ns max
Input Power	1.0	W max.
In/Out Impedance	50 Ω	
Operation Temperature Range	-40℃ to +85℃	

Mechanical Specification

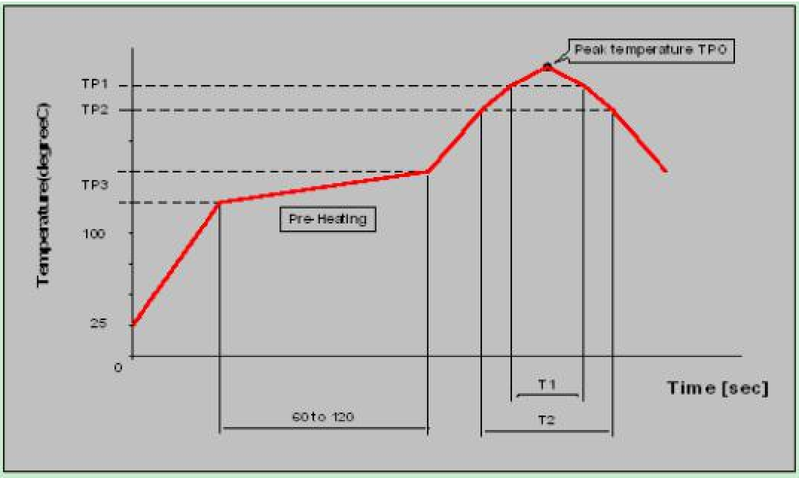


Plot Data



Recommanded PC Board Pattern

Soldering Condition



Measuring point of temperature : IN-OUT Terminals of The Device

Reflow Soldering : Both Convection and Infrared Rays, Hot Air and Hot Plate

Reflow standard condition	TPO (℃)	TP1 (℃)	T1 (s)	TP2 (℃)	T2 (s)	TP3 (℃)
Sn-3Ag-0.5 solder	245+/-5	220	30 to 60	___	___	150 to 180
Test condition of reflow heat resistance	260+5/-0	240	20	220	70	150 to 180